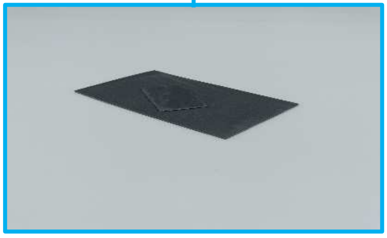
FT_TEL_160_YSS_30

Thermal Pad



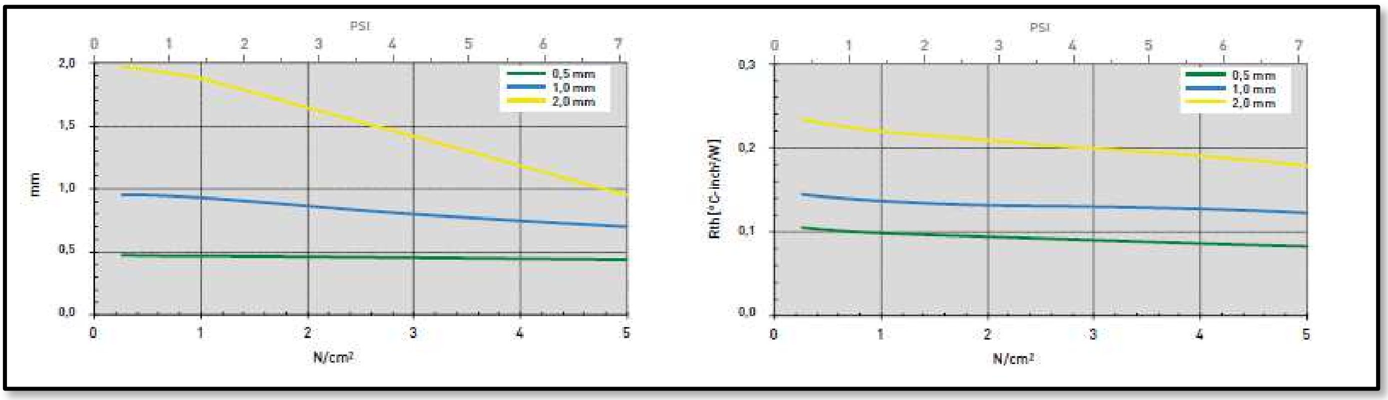
Our Thermal Foams also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that solve the problems of heat dissipation. The TEL_160_YSS is a mattress specially developed for applications where a low cooling requirement is required. Indeed, it is an excellent thermal conductor of 16W/ mK, with a good thermal resistance thus facilitating heat transfer and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	Unit	TEL_160_YSS			
Thickness	mm	0.5	1	2	-
Reinforcement	-	-			
Color	-	Black			
Hardness	Shore 00	40			
Size	mm	130*130			
Resistance @7.5 Psi	°C-inch²/W (mm)	0.083 (0.42)	0.124 (0.700)	0.180 (0.954)	-
Resistance @3.5 Psi		0.089 (0.45)	0.129 (0.785)	0.205 (1.150)	-
Resistance @1.5Psi		0.100 (0.47)	0.137 (0.934)	0.220 (1.874)	-
Thermal conductivity	W/mK	16			
Temperature	°C	-50 to 180			
Breakdown voltage	kV/mm	-			
Volume resistance	0hm - cm	< 50,000			
Contante dielectric	@1MHz	-			

The TEL_160_YSS is available in 0.5/1/1.5/2/3mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.